## MINIATURE POSITIVE ACTION SWITCHES

 Printed Circ uit Terminals
## FEATURES

- Sealed bushing
- Dry circuit (logic level loads) to power switching levels
- Two bushing and toggle lever sizes
- 1 and 2 pole circuitry
- Non-teasible mechanism for all but center "ON" circuits
- Wiping action contacts
- Positive make and break action
- Small and large size bushings and acutators
- Printed circuit board termination
- Two types of printed circuit board terminals
- straight
- formed

SPECIFCATIONS

- Bushing seal or bonded seal per MIL-S-8834
- MS approved and QPL'd to MIL-S-8834
- Temperature range: $-67^{\circ} \mathrm{F}$ to $+160^{\circ} \mathrm{F}$ $\left(-55^{\circ} \mathrm{C}\right.$ to $\left.+71^{\circ} \mathrm{C}\right)$
- Life: 20,000 operations at rated load 40,000 operations mechanical life
- "O" ring panel seal on $1 / 4$ "-40 type bushing size

| CURRENT RATINGS |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| No. of Poles | Catalog <br> Number | Type of Operation | 28 and 50VDC (Amperes per pole) |  | 115 VAC 60 Hz and 400 Hz (Amperes per pole) |  |
|  |  |  | Resistive Load 28VDC 50 VDC | Inductive Load 28VDC 50 VDC | Resistive Load 60 Hz 40 Hz | $\begin{gathered} \text { Inductive } \\ \text { Load } \\ 60 \mathrm{~Hz} 40 \mathrm{~Hz} \end{gathered}$ |
| 1 | $\begin{gathered} 8866 \\ \text { and } 8868 \end{gathered}$ | Maintained and Momentary | 51 | 1 - | 2 | 12 |
| 2 | $\begin{gathered} 8867 \\ \text { and } 8869 \end{gathered}$ | Maintained and Momentary | 5 | 1 - | 2 | 1 |

Minimum Rating: $25 \mu$ A at 5 millivolts or less.

SELECTION TABLE

$\star$ Momentary contact.
See page 77 for special circuit diagrams.
(1) Dielectric per MIL-S-8834 except limited to 1250 volts. Delayed action of the switch toggle lever may cause circuit to close or open before snap action mechanism trips.
(2) Caution should be exercised during soldering and flux removal. See page 62 for details.
(3) Furnished with Bonded Seal Feature. (Meets 15' head of water sealing level.)



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## CAUTION AND RECOMMENDATION FOR CLEANING AND SOLDERING

Contamination of the contacts of miniature switches is the most common cause of problems in low energy circuits,
resulting in the inability of current to flow through the increased resistance of the switch contacts.
As most contamination occurs during the installation and cleaning of the switch, proper care when installing the switch can
reduce problems in this area. The following procedures should be followed to reduce the possibility of switch contact conamination.

## Hand Solder

1. Use rosin core solder $.030^{\prime \prime}-.040^{\prime \prime}$ diameter.
2. A small soldering iron in the 30 to 40 watt range should be used.
3. The solder joint should not be overheated.
4. Do not position switch with terminations straight up.
5. No clean up should be necessary. However if used, do not allow solvents to enter non-sealed areas of switches.

## Wave Solder - Miniature Switches

Do not immerse or spray with solvents to remove flux except for switches designed for this type of cleaning.
The use of wave solder oil is not advised.

## OPTIONS/ACCESSORIES

- Special mounting hardware
- Special marking
- Mounting hardware furnished assembled
- Panel seal, Part Number 32-341 (15/32" - 32 bushing only)
- Special circuits
- Special bushing and lever plating
- Mounting adapter nut
- Custom wire harnesses
- EMI/RFI capability on two pole (15/32" - 32 bushing only)
- Gold plated contacts

15/32 DIA. BUSHING



